



Statement of Materials, Construction

Revision: 1.0
Date: 4-Mar-05

LEAD-FREE -- 18L-PDIP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.38466	Cu	7440-50-8	0.37427	30.15897	97.3
				Fe	7439-89-6	0.00904	0.72840	2.35
				Zn	7440-66-6	0.00046	0.03720	0.12
				P	7723-14-0	0.00012	0.00930	0.03
				Ag	7440-22-4	0.00077	0.06199	0.2
2	Die	Silicon Chip	0.00720	Si	7440-21-3	0.00716	0.57727	99.5
3	Die attach material	Conductive Epoxy	0.00125	Epoxy resin (5-25)	Proprietary	0.00019	0.01511	15
				Silver (70-85)	7440-21-3	0.00099	0.08008	79.5
				Aromatic Amine (1-10)	Proprietary	0.00007	0.00554	5.5
4	Wire	Gold	0.00385	Au	7440-57-5	0.00385	0.31020	99.99
5	Lead Finish	Tin	0.0109744	Sn	7440-31-5	0.01097	0.88432	100
6	Encapsulation	Epoxy Resin	0.83307	Fused Silica	7631-86-9	0.55982	45.11048	67.2
				Epoxy resin	29690-82-2	0.16661	13.42574	20
				Phenol Resin	9003-35-4	0.06248	5.03465	7.5
				Antimony trioxide	1309-64-4	0.02499	2.01386	3
				Brominated Epoxy Resin	40039-93-8	0.01666	1.34257	2
				Carbon Black	1333-86-4	0.00250	0.20139	0.3
Total Package weight			1.24100					

Note: Composition derived from MSDS and material C of C from Vendors;
 Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys